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SEMICONDUCTOR MEMORY DEVICE AND METHOD OF MANUFACTURING SEMICONDUCTOR MEMORY DEVICE

Abstract

A semiconductor memory device includes a substrate, a plurality of first conductive layers, a second conductive layer, a first pillar, and a second pillar. The plurality of first conductive layers are stacked over the substrate in a first direction. The second conductive layer is disposed over the plurality of first conductive layers. The first pillar extends inside the plurality of first conductive layers in the first direction. The first pillar includes a first semiconductor portion including a first semiconductor of single-crystal. The second pillar extends inside the second conductive layer in the first direction. The second pillar includes an insulating portion serving as an axis including an insulator and a second semiconductor portion which is disposed on an outer circumference of the insulating portion in view of the first direction. The second semiconductor portion is in contact with the first semiconductor portion and includes a second semiconductor of poly-crystal.

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Background/Summary

CROSS-REFERENCE TO RELATED APPLICATIONS [0001] This application is a continuation of and claims benefit under 35 U.S.C. § 120 to U.S. application Ser. No. 18/159,749, filed Jan. 26, 2023, which is a continuation of and claims benefit under 35 U.S.C. § 120 to U.S. application Ser. No. 16/987,712, filed Aug. 7, 2020, (now U.S. Pat. No. 11,594,545), which is based upon and claims the benefit of priority under 35 U.S.C. § 119 from Japanese Patent Application No. 2019-170454, filed Sep. 19, 2019, the entire contents of each of which are incorporated herein by reference.

FIELD
[0002] Embodiments described herein relate generally to a semiconductor memory device and a method for manufacturing a semiconductor memory device.
BACKGROUND
[0003] There have been developed NAND memory devices with three dimensional memory cell stacks.

Description

BRIEF DESCRIPTION OF THE DRAWINGS
[0004] FIG. **1** is a block diagram showing a system configuration of a semiconductor memory device of a first embodiment.
[0005] FIG. **2** is a schematic view showing an equivalent circuit of a memory cell array of the semiconductor memory device of the first embodiment.
[0006] FIG. **3** is a partial cross-sectional view of the memory cell array of the semiconductor memory device of the first embodiment.
[0007] FIG. **4** is a cross-sectional view showing a step involved in a manufacturing process for the memory cell array shown in FIG. **3**.
[0008] FIG. **5** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **3**.
[0009] FIG. **6** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **3**.
[0010] FIG. **7** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **3**.
[0011] FIG. **8** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **3**.
[0012] FIG. **9** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **3**.

[0013] FIG. **10** is a partial cross-sectional view of a memory cell array of a semiconductor memory device of a second embodiment.
[0014] FIG. **11** is a cross-sectional view showing a step involved in a manufacturing process for the memory cell array shown in FIG. **10**.
[0015] FIG. **12** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **10**.
[0016] FIG. **13** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **10**.
[0017] FIG. **14** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **10**.
[0018] FIG. **15** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **10**.
[0019] FIG. **16** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **10**.
[0020] FIG. **17** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **10**.
[0021] FIG. **18** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **10**.
[0022] FIG. **19** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **10**.
[0023] FIG. **20** is a partial cross-sectional view of a memory cell array of a semiconductor memory device of a third embodiment.
[0024] FIG. **21** is a cross-sectional view showing a step involved in a manufacturing process for the memory cell array shown in FIG. **20**.
[0025] FIG. **22** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **20**.
[0026] FIG. **23** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **20**.
[0027] FIG. **24** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **20**.
[0028] FIG. **25** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **20**.
[0029] FIG. **26** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **20**.
[0030] FIG. **27** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **20**.
[0031] FIG. **28** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **20**.
[0032] FIG. **29** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **20**.
[0033] FIG. **30** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **20**.
[0034] FIG. **31** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **20**.
[0035] FIG. **32** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **20**.
[0036] FIG. **33** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **20**.
[0037] FIG. **34** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **20**.

[0038] FIG. **35** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **20**.
[0039] FIG. **36** is a cross-sectional view showing a step involved in the manufacturing process for the memory cell array shown in FIG. **20**.

DETAILED DESCRIPTION

[0040] According to some embodiments, a semiconductor memory device may include, but not limited to, a substrate, a plurality of first conductive layers, a second conductive layer, a first pillar and a second pillar. The plurality of first conductive layers are stacked over the substrate in a first direction. The second conductive layer is disposed over the plurality of first conductive layers. The first pillar extends inside the plurality of first conductive layers in the first direction. The first pillar includes a first semiconductor portion including a first semiconductor of single-crystal. The second pillar extends inside the second conductive layer in the first direction. The second pillar includes an insulating portion as an axis including an insulator and a second semiconductor portion. The second semiconductor portion is disposed on an outer circumference of the insulating portion in view of the first direction. The second semiconductor portion is in contact with the first semiconductor portion. The second semiconductor portion includes a second semiconductor of poly-crystal.
[0041] Embodiments of a semiconductor memory device and a method of manufacturing a semiconductor memory device will hereinafter be described with reference to the accompanying drawings. In the following descriptions, components having the same function or similar functions are denoted by the same reference numerals and signs. Duplicate descriptions for components having the same function or similar functions may not omitted. In addition, the terms “parallel”, “orthogonal”, “same”, and “equivalence” used herein in the disclosure include “substantially parallel”, “substantially orthogonal”, “substantially same”, and “substantially equivalent”.
[0042] The term “connection” used in the disclosure is not limited only to physical connection but also includes electrical connection. That is, the term “connection” is not limited only to a case where two elements are in direct contact with each other but also includes an indirect contact where another member is present between two elements. The term “contact” used herein in the present specification means direct contact. The terms “overlap”, “face”, and “adjacent” used in the disclosure are not limited only to a case where two elements directly face each other or a case where two elements are in direct contact with each other, but also include another case where two elements indirectly face each other or one or more elements are present between the two elements.
[0043] In the following descriptions, a +X-direction (second direction), a −X-direction (second direction), a +Y-direction, and a −Y-direction are directions parallel to a surface **20***a* of a silicon substrate (substrate) **20** of a semiconductor memory device **1** of a first embodiment shown in FIG. **1**. The +X-direction is a direction from one string unit of the semiconductor memory device **1** to a string unit adjacent thereto through an insulating slit SLT. The −X-direction is a direction opposite to the +X-direction. In a case where the +X-direction and the −X-direction are not distinguished from each other, these directions will be simply referred to as an “X-direction”. The +Y-direction and the −Y-direction are directions intersecting the X-direction. The −Y-direction is a direction opposite to the +Y-direction. In a case where the +Y-direction and the −Y-direction are not distinguished from each other, these directions will be simply referred to as a “Y-direction”. The +Z-direction (first direction) and the −Z-direction (first direction) are directions intersecting the X-direction and the Y-direction. The +Z-direction is a direction parallel to a thickness direction of a silicon substrate **20**. The −Z-direction is a direction opposite to the +Z-direction. In a case where the +Z-direction and the −Z-direction are not distinguished from each other, these directions will be simply referred to as a “Z-direction”. The “+Z-direction” may be referred to as “upward” and the “−Z-direction” may be referred to as “downward”. Expressions of “upward” and “downward” are used for convenience and do not necessarily specify the direction of gravity. In the following embodiments, the +Z-direction is an example of a “first direction”. For example, when describing

that a portion is in the +Z-direction with respect to one component, description may be given using "over" and "upward" with respect to one component.

<Overall Configuration of Semiconductor Memory Device>

[0044] The semiconductor memory device **1** is a non-volatile semiconductor memory device and is, for example, a NAND flash memory. FIG. **1** is a block diagram of the semiconductor memory device **1**. As shown in FIG. **1**, the semiconductor memory device **1** includes, for example, at least one or more memory cells, a row decoder **11**, a sense amplifier **12**, and a sequencer **13**. Hereinafter, the semiconductor memory device **1** includes a memory cell array **10** including a plurality of memory cells.

[0045] The memory cell array **10** includes a plurality of blocks BLKO to BLKn. Here, n is an integer of 1 or greater and represents the order of the plurality of blocks BLK. Each of the plurality of blocks BLK is set of a plurality of non-volatile memory cell transistors. The memory cell array **10** is provided with a plurality of bit lines and a plurality of word lines. Each of the memory cell transistors is electrically connected to one bit line and one word line.

[0046] The row decoder **11** selects one block BLK on the basis of address information ADD received from an external memory controller (not shown) of the semiconductor memory device **1**. The row decoder **11** applies a desired voltage to each of a plurality of word lines to control a data write operation and a data read operation for the memory cell array **10**.

[0047] The sense amplifier **12** applies a desired voltage to each of a plurality of bit lines in accordance with data DAT received from the memory controller. The sense amplifier **12** determines data stored in a memory cell transistor on the basis of a voltage of a bit line and transmits the determined data DAT to the memory controller. The sequencer **13** controls the overall operation of the semiconductor memory device **1** on the basis of a command CMD received from the memory controller.

<Electrical Configuration of Memory Cell Array>

[0048] FIG. **2** is a diagram showing an equivalent circuit of the memory cell array **10** and shows one block BLK. The block BLK includes, for example, a plurality of string units SU. In FIG. **2**, for example, four string units SU**0** to SU**2** are shown.

[0049] Each of the plurality of string units SU is a set of a plurality of NAND strings NS. One end of each of the plurality of NAND strings NS is connected to any one of a plurality of bit lines BL**0** to BLm. Here, m is an integer of 1 or greater and represents the order of the plurality of bit lines BL. The other end of each of the plurality of NAND strings NS is connected to a source line SL. Each of the plurality of NAND strings NS includes, for example, a plurality of memory cell transistors MT, a first selected transistor ST**1**, and a second selected transistor ST**2**. The NAND string NS includes, for example, 15 memory cell transistors MT**0** to MT**14**.

[0050] The plurality of memory cell transistors MT are connected to each other in series. Each of the plurality of memory cell transistors MT includes, for example, a control gate and a charge storage film and stores data in a non-volatile manner. Each of the plurality of memory cell transistors MT stores charge in the charge storage film in accordance with a voltage applied to the control gate. A control gate of each of the plurality of memory cell transistors MT is connected to any one of a plurality of word lines WL. In FIG. **2**, **15** word lines WL**0** to WL**14** are shown. Each of the plurality of memory cell transistors MT is electrically connected to the row decoder **11** through a corresponding word line WL.

[0051] The first selected transistor ST**1** is provided between the plurality of memory cell transistors MT and the corresponding bit line BL. A drain of the first selected transistor ST**1** is connected to the bit line BL. A source of the first selected transistor ST**1** is connected to the plurality of memory cell transistors MT. A control gate of the first selected transistor ST**1** is connected to a corresponding selected gate line SGD. In FIG. **2**, the selected gate line SGD corresponding to the control gate of the first selected transistor ST**1** is any one of selected gate lines SGDO to SGD**2**. The first selected transistor ST**1** is connected to the row decoder **11** through the selected gate line

SGD. The first selected transistor ST**1** connects the NAND string NS and the bit line BL to each other when a predetermined voltage is applied to the selected gate line SGD.
[0052] The second selected transistor ST**2** is provided between the plurality of memory cell transistors MT and the source line SL. A drain of the second selected transistor ST**2** is connected to the plurality of memory cell transistors MT. A source of the second selected transistor ST**2** is connected to the source line SL. A control gate of the second selected transistor ST**2** is connected to a selected gate line SGS. The second selected transistor ST**2** is connected to the row decoder **11** through the selected gate line SGS. The second selected transistor ST**2** connects the NAND string NS and the source line SL to each other when a predetermined voltage is applied to the selected gate line SGS.
<Overall Configuration of Memory Cell Array>
[0053] Each of the plurality of string units SU extends in the Y-direction. In the X-direction, the plurality of string units SU are separated from each other by a slit SLT filled with an insulating material.
[0054] FIG. **3** is a cross-sectional view of a portion of the memory cell array **10** of the semiconductor memory device **1** of the first embodiment. The memory cell array **10** includes, for example, a silicon substrate **20**, a first stack **22**, a second stack **24**, a first pillar **40**, a first insulating film **52**, a first charge storage film **54**, a second insulating film **56**, a second pillar **60**, a third stack **122**, a third insulating film **72**, a second charge storage film **74**, a fourth insulating film **76**, a third insulating layer **30**, a contact plug BLC, and a bit line BL. FIG. **3** shows two first columnar bodies **40**, two second columnar bodies **60**, and a contact plug BLC and a bit line BL connected to one second pillar **60**.
[0055] The first stack **22** is provided on the surface **20***a* of the silicon substrate **20**. The first stack **22** includes, for example, a plurality of first conductive layers **23** and a plurality of first insulating layers **25**. The plurality of first conductive layers **23** include a conductive layer **31** and at least one conductive layer **32** and includes, for example, a plurality of conductive layers **32**. The plurality of first insulating layers **25** include at least one insulating layer **34** and includes, for example, a plurality of insulating layers **34**. The conductive layers **31** and **32** and the insulating layer **34** are alternately stacked in the Z-direction.
[0056] The conductive layer **31** is provided closest to the −Z side in the first stack **22** and functions as the selected gate line SGS. The plurality of conductive layers **32** function as the word lines WL**0** to WL**14**. The conductive layer **31** and each of the plurality of conductive layers **32** are formed to have a plate shape in the X-direction and the Y-direction. The conductive layer **31** and each of the plurality of conductive layers **32** are formed of, for example, tungsten (W).
[0057] The insulating layer **34** is provided between the conductive layer **31** and the conductive layer **32** provided closest to the silicon substrate **20** in the −Z-direction among the plurality of conductive layers **32** in the Z-direction and between two conductive layers **32** adjacent to each other in the Z-direction. Each of the plurality of insulating layers **34** is formed to have a plate shape in the X-direction and the Y-direction. The insulating layer **34** is formed of, for example, silicon oxide (SiO.sub.2).
[0058] Each of two first columnar bodies **40** extends inside the first stack **22** in the Z-direction. Each of the two first columnar bodies **40** extends in the X-direction and the Y-direction toward the +Z-direction.
[0059] Each of the two first columnar bodies **40** includes a first channel portion **42**. The first channel portion **42** extends inside the first stack **22** in the Z-direction and is adjacent to the plurality of conductive layers (the plurality of first conductive layers) **32** in the X-direction. The first channel portion **42** functions as a channel of a transistor constituting the NAND string NS.
[0060] Each of the two first columnar bodies **40** includes, for example, a first end **40***e* and a second end **40***f*. The first end **40***e* is an end which is adjacent to a plurality of conductive layers **32** on a first side in the X-direction in each of the two first columnar bodies **40**. The X-direction is an

example of a second direction intersecting the Z-direction. The second end **40***f* is an end which is adjacent to a plurality of conductive layers **32** on a second side opposite to the first side in the X-direction in each of the two first columnar bodies **40**. In FIG. **3**, the first end **40***e* and the second end **40***f* in the X-direction seen from the Y-direction are shown. When seen in the −Z-direction, the first channel portion **42** includes, for example, a first semiconductor portion **48** in a region **44** including a center **40***c* equidistant from the first end **40***e* and the second end **40***f*. The first semiconductor portion **48** includes a first semiconductor of single-crystal. The first semiconductor of single-crystal includes, for example, single-crystal silicon, single-crystal silicon germanium (SiGe), single-crystal germanium (Ge), or a single-crystal III-V semiconductor such as gallium arsenide (GaAs) or indium gallium arsenide (InGaAs).
[0061] Each of the two first columnar bodies **40** includes semiconductor portions **35** and **36**. The semiconductor portion **35** is adjacent to the silicon substrate **20** in the Z-direction and is an example of a first portion. The semiconductor portion **36** extends to a side opposite to the silicon substrate **20** in the Z-direction from the semiconductor portion **35** and is an example of a second portion. Each of the semiconductor portions **35** and **36** includes a first semiconductor of single-crystal. In the X-direction, the semiconductor portion **36** has a maximum width smaller than the minimum width of the semiconductor portion **35** in the X-direction. In other words, the minimum width of the semiconductor portion **35** in the X-direction is smaller than the maximum width of the semiconductor portion **36** in the X-direction.
[0062] The first insulating film **52** is provided between each of the plurality of first conductive layers **23** and the first channel portion **42** in the X-direction. The first insulating film **52** applies a current generated by the first channel portion **42** by a tunnel effect to the first charge storage film **54**. The first insulating film **52** is formed of, for example, silicon oxide or the like.
[0063] The first charge storage film **54** is provided between each of the plurality of first conductive layers **23** and the first insulating film **52** in the X-direction. The first charge storage film **54** stores charge in accordance with a voltage applied to a selected gate line SGD. The first charge storage film **54** is formed of an insulator such as silicon nitride.
[0064] The second insulating film **56** is provided between each of the plurality of first conductive layers **23** and the first charge storage film **54** in the X-direction. A phenomenon in which charge is moved from the plurality of first conductive layers **23** to the first charge storage film **54** or the first channel portion **42** is prevented. The second insulating film **56** is formed of, for example, silicon oxide, aluminum oxide, zirconium oxide, or the like.
[0065] In the Z-direction, the semiconductor portion **35** is provided between each of the two first columnar bodies **40** and the silicon substrate **20**. The semiconductor portion **35** is in contact with the first channel portion **42** and in contact with the first semiconductor portion **48** in the Z-direction. The semiconductor portion **35** includes the same material as that of the first semiconductor portion **48** and is formed of, for example, single-crystal silicon.
[0066] The second stack **24** is provided on a side opposite to the silicon substrate **20** with respect to the first stack **22** in the Z-direction. The second stack **24** includes, for example, at least one second conductive layer **26** and at least one second insulating layer **28**. The second stack **24** includes, for example, two second conductive layers **26**. Each of the two second conductive layers **26** functions as a selected gate line SGD. Each of the two second conductive layers **26** is formed of, for example, tungsten. One second insulating layer **28** is formed, for example, silicon oxide.
[0067] Each of the two second columnar bodies **60** is a pillar connected to each of the two first columnar bodies **40** in the Z-direction. Each of the two second columnar bodies **60** extends inside the second stack **24** in the Z-direction. Each of the two second columnar bodies **60** extends in the X-direction and the Y-direction toward the +Z-direction. An end face of each of the two second columnar bodies **60** on a first side in the X-direction is positioned substantially in alignment with an end face of each of the two first columnar bodies **40** on a first side in the X-direction. An end face of each of the two second columnar bodies **60** on a second side in the X-direction is positioned

substantially in alignment with an end face of each of the two first columnar bodies **40** on a second side in the X-direction.

[0068] Each of the two second columnar bodies **60** includes a second channel portion **62**. The second channel portion **62** extends inside the second stack **24** in the Z-direction and is adjacent to the two second conductive layers **26** in the X-direction. The minimum length of the first channel portion **42** in the Z-direction is larger than the minimum length of the second channel portion **62** in the Z-direction.

[0069] Each of the two second columnar bodies **60** includes, for example, a third end **60***e* and a fourth end **60***f*. The third end **60***e* is an end which is adjacent to the two second conductive layers **26** on a first side in the X-direction in each of the two second columnar bodies **60**. The fourth end **60***f* is an end which is adjacent to the two second conductive layers **26** on a second side in the X-direction in each of the two second columnar bodies **60**. The second channel portion **62** includes, for example, an insulating portion **70**. The insulating portion **70** serves as an axis including an insulator such as silicon oxide and is provided in a region **64** including a center **60***c* equidistant from the third end **60***e* and the fourth end **60***f* when seen in the −Z-direction.

[0070] Each of the two second columnar bodies **60** includes, for example, a second semiconductor portion **68** between the insulating portion **70** and the two second conductive layers **26** in the X-direction. The second semiconductor portion **68** is disposed on the outer circumference of the insulating portion **70** in view of the Z-direction. The second semiconductor portion **68** includes a second semiconductor of poly-crystal. The second semiconductor of poly-crystal includes, for example, polycrystalline silicon, polycrystalline silicon germanium (SiGe), polycrystalline germanium (Ge), or a polycrystalline III-V semiconductor such as gallium arsenide (GaAs) or indium gallium arsenide (InGaAs).

[0071] The third insulating film **72** is provided between each of the two second conductive layers **26** and the second channel portion **62**. The third insulating film **72** is in contact with the first insulating film **52** in the Z-direction and is formed of a film integrally with the first insulating film **52**. The third insulating film **72** includes the same material as that of the first insulating film **52** and is formed of, for example, silicon oxide or the like.

[0072] The second charge storage film **74** is provided between each of the two second conductive layers **26** and the third insulating film **72**. The second charge storage film **74** is in contact with the first charge storage film **54** in the Z-direction and is formed of a film integrally with the first charge storage film **54**. The second charge storage film **74** includes the same material as that of the first charge storage film **54** and is formed of an insulator such as silicon nitride.

[0073] The fourth insulating film **76** is provided between each of the two second conductive layers **26** and the second charge storage film **74**. The fourth insulating film **76** is in contact with the second insulating film **56** in the Z-direction and is formed of a film integrally with the second insulating film **56**. The fourth insulating film **76** includes the same material as that of the second insulating film **56** and is formed of, for example, silicon oxide, aluminum oxide, zirconium oxide, or the like.

[0074] The third stack **122** is provided between the silicon substrate **20** and the first stack **22** in the Z-direction. The third stack **122** includes, for example, a third conductive layer **131**, a fourth insulating layer **132**, and a fifth insulating layer **133**. The fourth insulating layer **132** is provided between the third conductive layer **131** and the first stack **22** in the Z-direction. The fifth insulating layer **133** is provided between the third stack **122** and the silicon substrate **20**. The minimum thickness of the fourth insulating layer **132** in the Z-direction is larger than the minimum thickness of one first insulating layer **25** included in the plurality of first insulating layers **25** in the Z-direction.

[0075] The third insulating layer **30** is provided between the plurality of first conductive layers **23** and at least one second conductive layer **26** in the Z-direction. The minimum thickness of the third insulating layer **30** in the Z-direction is larger than the maximum thickness of one insulating layer

34 included in the plurality of first insulating layers **25**.

[0076] The contact plug BLC is in contact with the second channel portion **62** in the Z-direction. The bit line BL is in contact with the contact plug BLC in the Z-direction and extends in the X-direction. Each of the contact plug BLC and the bit line BL is formed of, for example, tungsten.

<Method of Manufacturing Memory Cell Array>

[0077] Next, a method of manufacturing the memory cell array **10** of the semiconductor memory device **1** will be briefly described. The method of manufacturing the memory cell array **10** of the semiconductor memory device **1** includes a first intermediate stack forming process, a hole forming process, a first semiconductor material supply process, a second intermediate stack forming process, a second semiconductor material supply process, and an insulating material supply process. Hereinafter, each of the over-described processes will be described in detail.

[0078] First, in the first intermediate stack forming process, first dummy layers **238** and first insulating layers **234** are alternately stacked on the surface **20***a* of the silicon substrate **20** in the Z-direction to form a first intermediate stack **240**. The first dummy layer **238** is formed of, for example, silicon nitride. The first insulating layer **234** includes the same material as that of the first insulating layer **25** and is formed of, for example, silicon oxide. An insulating layer **230** is formed on a surface **240***a* of the first intermediate stack **240**. The insulating layer **230** is formed of, for example, silicon oxide. The minimum thickness of the insulating layer **230** in the Z-direction is larger than the maximum thickness of the first dummy layer **238** in the Z-direction. The first intermediate stack **240** includes the third stack **122** and the first stack **22** in the Z-direction.

[0079] Subsequently, in the second intermediate stack forming process, a second intermediate stack **244** including at least one second dummy layer **258** and at least one second insulating layer **228** is formed on a surface **230***a* of the insulating layer **230**. That is, the second intermediate stack **244** is formed on a side opposite to the silicon substrate **20** with respect to the first intermediate stack **240** in the Z-direction. An insulating layer **239** is formed on a surface **244***a* of the second intermediate stack **244**. The insulating layer **239** is formed of, for example, silicon oxide. The minimum thickness of the insulating layer **239** in the Z-direction is larger than the maximum thickness of the first dummy layer **238** in the Z-direction.

[0080] FIG. **4** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10** and showing a hole forming process. In the hole forming process, for example, a hole H**1** extending in the Z-direction is formed in the first intermediate stack **240**, the insulating layer **230**, the second intermediate stack **244**, and the insulating layer **239** as shown in FIG. **4** through patterning, etching, and the like. The hole H**1** serves as both a first hole extending in the Z-direction in the first intermediate stack **240** and a second hole extending in the Z-direction in the second intermediate stack **244** so as to be connected to the first hole in substantially the entirety thereof (at least a portion) in the X-direction. In other words, in the manufacture of the semiconductor memory device **1**, the first hole and the second hole are formed in the same process.

[0081] FIG. **5** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10**. The bottom face of the hole H**1** is positioned forward in the −Z-direction from the surface **20***a* of the silicon substrate **20**. That is, a concave portion **229** is formed in the surface **20***a* of the silicon substrate **20** by forming the hole H**1**. Subsequently, the semiconductor portion **35** is formed in the concave portion **229**. A surface **35***a* of the semiconductor portion **35** is positioned forward in the +Z-direction from the surface **20***a* of the silicon substrate **20**.

[0082] Subsequently, an insulating film **256**, a semiconductor film **254**, and an insulating film **252** are sequentially formed on a surface **239***a* of the insulating layer **239**, and a side surface **239***s* of the insulating layer **239**, a side surface **240***s* of the first intermediate stack **240**, and a surface **235***a* of the semiconductor portion **235** which are exposed to the hole H**1**. The insulating film **256** includes the same material as that of the second insulating film **56**. The semiconductor film **254** includes the same material as that of the first charge storage film **54**. The insulating film **252** includes the same material as that of the first insulating film **52**.

[0083] Subsequently, the insulating film **256**, the semiconductor film **254**, and the insulating film **252** on the surface **35***a* of the semiconductor portion **35** are removed, and the insulating film **256**, the semiconductor film **254**, and the insulating film **252** are separated from each other in the X-direction. A portion of the surface **35***a* being exposed is dug down into in the −Z-direction to form the concave portion **229**. After the concave portion **229** is formed, a hole H**1-2** extending in the Z-direction is formed.
[0084] FIG. **6** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10** and showing a first semiconductor material supply process. In the first semiconductor material supply process, a first semiconductor of single-crystal is supplied to a first region R**1** of the hole H**1-2** in the Z-direction. The first region R**1** includes a center C**1** which is equidistant from a first end E**1** of the hole H**1-2** and a second end E**2** of the hole H**1-2** on a side opposite to the first end E**1** in the X-direction. The first semiconductor of single-crystal includes the same material as that of the first semiconductor portion **48** and is, for example, single-crystal silicon. In detail, the first semiconductor of single-crystal is grown in the first region R**1** in an epitaxial manner from a surface **35***g* of the semiconductor portion **35** which faces the concave portion **229** to form a semiconductor portion **242**. A surface **242***a* of the semiconductor portion **242** is positioned forward from a surface **252***a* of the insulating film **252** in the +Z-direction. The semiconductor portion **242** in the first region R**1** protrudes further in the +Z-direction than the semiconductor portion **242** in the vicinity of the first region R**1** in the X-direction.
[0085] FIG. **7** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10** and showing a process of partially removing a first semiconductor material. For example, the semiconductor portion **242** is polished while being removed in the −Z-direction through chemical mechanical polishing (CMP), and the surface **242***a* of the semiconductor portion **242** is aligned on substantially the same plane as the surface **252***a* of the insulating film **252** in the Z-direction.
[0086] FIG. **8** is a cross-sectional view showing an example of a manufacturing process of the memory cell array **10** and showing a process of recessing a first semiconductor material. For example, the semiconductor portion **242** is recessed through dry etching so that the surface **242***a* of the semiconductor portion **242** is positioned in the Z-direction between the surface **230***a* of the insulating layer **230** in the +Z-direction and a surface **230***b* of the insulating layer **230** in the −Z-direction. The first semiconductor portion **48** constituting the first channel portion **42** is formed by recessing the semiconductor portion **242** as shown in FIG. **8**. A hole H**1-3** is formed further in the +Z-direction than the first semiconductor portion **48**. The hole H**1-3** extends in the Z-direction in the second intermediate stack **244**, and at least a portion of the hole is connected to a first hole in the X-direction. The hole H**1-3** is an example of a second hole.
[0087] FIG. **9** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10** and showing a second semiconductor material supply process. In the second semiconductor material supply process, as shown in FIG. **9**, a second semiconductor of poly-crystal is supplied between a second region R**2**, including a center C**2** equidistant from a third end E**3** of the hole H**1-3** and a fourth end E**4** on a side opposite to the third end of the second hole in the X-direction, and the second intermediate stack **244** in the Z-direction. In more detail, a semiconductor film **262** is formed in the surface **252***a* of the insulating film **252**, and a side surface **252***s* of the insulating film **252** and a surface **48***a* of the first semiconductor portion **48** which are exposed to the hole H**1-3**. The semiconductor film **262** includes the same material as that of the second semiconductor portion **68**, is formed of a second semiconductor of poly-crystal, and is formed of, for example, polycrystalline silicon.
[0088] Subsequently, although not shown in the drawing, an insulating material is supplied to the second region R**2** in the Z-direction. The insulating material includes the same material as that of the insulating portion **70**. The insulating material is recessed in the −Z-direction, and a second semiconductor of poly-crystal is supplied to the second region R**2** in the +Z-direction rather than an

insulating material.

[0089] The insulating film **252**, the semiconductor film **254**, and the insulating film **256** in the −Z-direction from positions overlapping the surface **48***a* of the first semiconductor portion **48** in the Z-direction function as the first insulating film **52**, the first charge storage film **54**, and the second insulating film **56**, respectively. The insulating film **252**, the semiconductor film **254**, and the insulating film **256** in the +Z-direction from positions overlapping the surface **48***a* of the first semiconductor portion **48** in the Z-direction function as the third insulating film **72**, the second charge storage film **74**, and the fourth insulating film **76**, respectively.

[0090] Subsequently, although not shown in the drawing, the plurality of first dummy layers **238** of the first intermediate stack **240** and the plurality of second dummy layers **258** of the second intermediate stack **244** are removed using, for example, a chemical solution or the like. A conductive material including the same material as that of the first conductive layer **23** is supplied to a region from which each of the first dummy layers **238** is removed. A conductive material including the same material as that of the second conductive layer **26** is supplied to a region from which each of the second dummy layers **258** is removed.

[0091] The memory cell array **10** shown in FIG. **3** can be manufactured by proceeding with the over-described processes. The semiconductor memory device **1** is formed by performing known pre-processing before the over-described processes and performing known post-processing after the over-described processes. However, the method of manufacturing the semiconductor memory device **1** is not limited to the over-described method.

[0092] Operational effects of the semiconductor memory device **1** of the first embodiment described over will be described. In the semiconductor memory device of the related art, a polycrystalline semiconductor material is used for a material of a channel portion. The polycrystalline semiconductor material includes, for example, polycrystalline silicon. The polycrystalline semiconductor material has a plurality of defect levels at grain boundaries, and the like. The polycrystalline semiconductor material has a plurality of defect levels, which results in a deterioration in electrical characteristics. The semiconductor memory device **1** of the first embodiment includes the first semiconductor portion **48** including a first semiconductor of single-crystal with a defect level of hardly any defects in the region **44** including the center **40***c* equidistant from the first end **40***e* and the second end **40***f* when seen in the Z-direction. The first channel portion **42** is formed of a first semiconductor of single-crystal with a defect level of hardly any defects, so that variations in a threshold voltage of a plurality of memory cell transistors MT are suppressed. Therefore, according to the semiconductor memory device **1**, electrical characteristics can be improved.

[0093] The semiconductor memory device **1** of the first embodiment includes the insulating portion **70** in the region **64** including the center **60***c* equidistant from the third end **60***e* and the fourth end **60***f* when seen in the −Z-direction. The semiconductor memory device **1** includes the second semiconductor portion **68** including a second semiconductor of poly-crystal between the insulating portion **70** and the two second conductive layers **26** functioning as a selected gate line SGD in the X-direction. Since the second channel portion **62** adjacent to the selected gate line SGD in the X-direction has a thin film channel having a hollow structure, the second channel portion includes a second semiconductor of poly-crystal, but a deterioration in cut-off characteristics is suppressed and the occurrence of a defective operation of the selected gate line SGD is prevented. Therefore, according to the semiconductor memory device **1**, electrical characteristics can be improved.

Second Embodiment

[0094] Next, a configuration of a semiconductor memory device according to a second embodiment will be described. Although not shown in the drawing, the semiconductor memory device of the second embodiment is a NAND flash memory, similar to the semiconductor memory device **1** of the first embodiment. Hereinafter, with regard to components of the semiconductor memory device of the second embodiment, only contents different from those of the components of

the semiconductor memory device **1** will be described, and a detailed description of contents which are common to those of the components of the semiconductor memory device **1** will be omitted.
[0095] FIG. **10** is a cross-sectional view of a portion of a memory cell array **10-2** of the semiconductor memory device of the second embodiment. As shown in FIG. **10**, a second stack **24** includes, for example, three second conductive layers **26**. When seen in the −Z-direction, for example, a silicon oxide film is provided in a region **64** including a center **60***c* as an insulating portion **70**. A gap not shown in the drawing may remain in the silicon oxide film. Each of two second columnar bodies **60** includes a third insulating film **72**, a second charge storage film **74**, and a fourth insulating film **76** similar to the first embodiment. However, the third insulating film **72** is formed as a film different from a first insulating film **52**. The second charge storage film **74** is formed as a film different from a first charge storage film **54**. The fourth insulating film **76** is formed as a film different from a second insulating film **56**. In the second embodiment, a stacked film of the third insulating film **72**, the second charge storage film **74**, and the fourth insulating film **76** functions as an insulating portion.
[0096] The three second conductive layers **26** and at least one or more second insulating layers **28** between the two second columnar bodies **60** in the X-direction are separated from each other in the X-direction by a groove **290** extending in the Z-direction. The groove **290** is provided with an insulator not shown in the drawing. The three second conductive layers **26** on a first side of each of the two second columnar bodies **60** in the X-direction may be separated from each other in the X-direction.
[0097] Next, a method of manufacturing the memory cell array **10-2** of the semiconductor memory device of the second embodiment will be briefly described. The method of manufacturing the memory cell array **10-2** of the semiconductor memory device of the second embodiment includes a first intermediate stack forming process, a first hole forming process, a first semiconductor material supply process, a second intermediate stack forming process, a second hole forming process, a second semiconductor material supply process, and an insulating material supply process.
[0098] First, although not shown in the drawing, first dummy layers **238** and first insulating layers **234** are alternately stacked on the surface **20***a* of the silicon substrate **20** in the Z-direction to form a first intermediate stack **240** in the first intermediate stack forming process described in the first embodiment. Subsequently, a first hole extending in the Z-direction is formed in a first intermediate stack **240** and an insulating layer **230** in the first hole forming process without performing the second intermediate stack forming process. Thereafter, as described in the first embodiment, a semiconductor portion **35**, a first insulating film **52**, a first charge storage film **54**, a second insulating film **56**, and a first semiconductor portion **48** are formed in the first hole.
[0099] FIG. **11** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10-2** and showing a first plural material recessing process. In detail, the surface of a component after forming the first semiconductor portion **48** in the first hole is polished while being removed in the −Z-direction through, for example, CMP, and a surface **230***a* of the insulating layer **230**, a surface **52***a* of the first insulating film **52** extending in the Z-direction, a surface **54***a* of the first charge storage film **54** extending in the Z-direction, a surface **56***a* of the second insulating film **56** extending in the Z-direction, and a surface **48***a* of the first semiconductor portion **48** are aligned with each other on the same plane. The same plane is set to be a surface **300**.
[0100] FIG. **12** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10-2** and showing a second intermediate stack forming process. In the second intermediate stack forming process, as shown in FIG. **12**, a second intermediate stack **244** including three second dummy layers **258** and at least one second insulating layer **228** is formed on the surface **300**.
[0101] FIG. **13** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10-2** and showing a second hole forming process. In the second hole forming process, as shown in FIG. **13**, a second hole H**2** extending in the Z-direction is formed in the

second intermediate stack **244**. At least a portion of the second hole H**2** is connected to a first hole H**1** and the first semiconductor portion **48** in the X-direction. That is, in the second embodiment, the first hole H**1** and the second hole H**2** are formed in different processes.

[0102] FIG. **14** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10-2**. Subsequently, an insulating film **286**, a semiconductor film **284**, and an insulating film **282** are sequentially formed in a surface **244***a* of the second intermediate stack **244**, and a side surface **244***s* of the second intermediate stack **244**, a surface **48***a* of the first semiconductor portion **48**, and the like which are exposed to the hole H**2**. The insulating film **286** includes the same material as that of the fourth insulating film **76**. The semiconductor film **284** includes the same material as that of the second charge storage film **74**. The insulating film **282** includes the same material as that of the third insulating film **72**.

[0103] FIG. **15** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10-2**. Subsequently, the insulating film **286**, the semiconductor film **284**, and the insulating film **282** on the surface **48***a* of the first semiconductor portion **48** are removed, and the insulating film **286**, the semiconductor film **284**, and the insulating film **282** are separated from each other in the X-direction. A portion of the exposed surface **48***a* of the first semiconductor portion **48** is dug down in the −Z-direction to form a concave portion **289**. After the concave portion **289** is formed, a hole H**2-2** extending in the Z-direction is formed.

[0104] In the second semiconductor material supply process, as shown in FIG. **15**, a second semiconductor of poly-crystal is supplied between a second region R**2**, including a center C**2** equidistant from a third end E**3** and a fourth end E**4** of the hole H**2-2** in the X-direction, and the second intermediate stack **244** in the Z-direction. FIG. **16** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10-2** and showing a second semiconductor material supply process. In detail, as shown in FIG. **16**, a semiconductor portion **266** including a second semiconductor of poly-crystal is formed in the surface **244***a* of the second intermediate stack **244**, and a side surface **282***s* of the insulating film **282** and the surface **48***a* of the first semiconductor portion **48** which are exposed to the hole H**2-2**.

[0105] Subsequently, although not shown in the drawing, for example, a silicon oxide film is formed in the second region R**2** inside the semiconductor portion **266** in the Z-direction as an insulating portion **71**. A gap not shown in the drawing may remain in the silicon oxide film. FIG. **17** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10-2**. As shown in FIG. **17**, the surface of a component after forming the second semiconductor portion **68** is polished while being removed in the −Z-direction through, for example, CMP, and the surfaces of the second intermediate stack **244**, the semiconductor portion **266**, the insulating film **286**, the semiconductor film **284**, and the insulating film **282** are aligned with each other on the same plane. When the same plane is set to be a surface **310**, an insulating interlayer **350** including silicon oxide or the like is formed on the surface **310**.

[0106] Subsequently, the plurality of first dummy layers **238** of the first intermediate stack **240** and the plurality of second dummy layers **258** of the second intermediate stack **244** are removed using, for example, a medicinal solution or the like. A conductive material including the same material as that of the first conductive layer **23** is supplied to a region **331** from which each of the first dummy layers **238** is removed. A conductive material including the same material as that of the second conductive layer **26** is supplied to a region **332** from which each of the second dummy layers **258** is removed. FIG. **18** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10-2** and showing components before the groove **290**, a contact plug BLC, and a bit line BL shown in FIG. **10** are formed.

[0107] FIG. **19** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10-2** and showing an insulating slit forming process. As shown in FIG. **19**, the groove **290** penetrating the second stack **24** in the Z-direction between two predetermined second columnar bodies **60** adjacent to each other in the X-direction, among the plurality of second columnar bodies **60**, is formed. An insulating material such as silicon oxide is supplied to the groove **290**, and the surface of the insulating material is aligned with a surface **350***a* of the insulating interlayer **350** on the same plane. The surface of the insulating material and the surface **350***a* of the insulating interlayer **350** are aligned with each other on the same plane to form an insulating slit **360** in the groove **290**.

[0108] The memory cell array **10-2** shown in FIG. **10** can be manufactured by proceeding with the over-described processes. The semiconductor memory device of the second embodiment is formed by performing known pre-processing before the over-described processes and performing known post-processing after the over-described processes. However, the method of manufacturing the semiconductor memory device of the second embodiment is not limited to the over-described method.

[0109] Operational effects of the semiconductor memory device of the second embodiment described over will be described. Similarly to the semiconductor memory device **1** of the first embodiment, the semiconductor memory device of the second embodiment includes the first semiconductor portion **48** including a first semiconductor of single-crystal with a defect level of hardly any defects in a region **44** including a center **40***c* equidistant from a first end **40***e* and a second end **40***f* when seen in the Z-direction. A first channel portion **42** is formed of a first semiconductor of single-crystal with a defect level of hardly any defects, so that variations in a threshold voltage of a plurality of memory cell transistors MT are suppressed. Therefore, according to the semiconductor memory device of the second embodiment, electrical characteristics can be improved.

[0110] The semiconductor memory device of the second embodiment includes the insulating portion **70** in a region **64** including a center **60***c* equidistant from a third end **60***e* and a fourth end **60***f* when seen in the Z-direction. The semiconductor memory device of the second embodiment includes the second semiconductor portion **68** including a second semiconductor of poly-crystal between the insulating portion **70** and two second conductive layers **26** functioning as a selected gate line SGD in the X-direction. Since a second channel portion **62** adjacent to the selected gate line SGD in the X-direction has a thin film channel having a hollow structure, a deterioration in cut-off characteristics is suppressed and the occurrence of a defective operation of the selected gate line SGD is prevented. Therefore, according to the semiconductor memory device of the second embodiment, electrical characteristics can be improved.

Third Embodiment

[0111] Next, a configuration of a semiconductor memory device according a third embodiment will be described. Although not shown in the drawing, the semiconductor memory device of the third embodiment is a NAND flash memory, similar to the semiconductor memory device **1** of the first embodiment and the semiconductor memory device of the second embodiment. Hereinafter, with regard to components of the semiconductor memory device of the third embodiment, only contents different from those of the components of the semiconductor memory device of the second embodiment will be described, and detailed description of contents common to the contents of the components of the semiconductor memory device of the second embodiment will be omitted.

[0112] FIG. **20** is a cross-sectional view of a portion of a memory cell array **10-3** of the semiconductor memory device of the third embodiment. As shown in FIG. **20**, a second stack **24** includes, for example, one second conductive layer **26**. The minimum thickness of the second conductive layer **26** in the Z-direction is larger than the maximum thickness of one first conductive layer **23** in the Z-direction and is larger than the maximum thickness of a conductive layer **32** in the Z-direction. Specifically, the minimum thickness of one second conductive layer **26** in the Z-direction is larger than twice the maximum thickness of one first conductive layer **23** in the Z-direction.

[0113] A semiconductor film **92** is provided between a fifth insulating film **82** and a second conductive layer **26** adjacent to each other from a first side of a second semiconductor portion **68** in the X-direction. An insulating film **93** is provided between the semiconductor film **92** and the second conductive layer **26** in the X-direction. A semiconductor film **94** is provided between the fifth insulating film **82** and the second conductive layer **26** adjacent to each other from a second side of the second semiconductor portion **68** in the X-direction. Each of the semiconductor films **92** and **94** is formed of, for example, amorphous silicon (aSi).

[0114] Next, a method of manufacturing the memory cell array **10-3** of the semiconductor memory device of the third embodiment will be briefly described. The method of manufacturing the memory cell array **10-3** of the semiconductor memory device of the third embodiment includes a first intermediate stack forming process, a first hole forming process, a first semiconductor material supply process, a second intermediate stack forming process, a second hole forming process, a second semiconductor material supply process, and an insulating material supply process. That is, when the memory cell array **10-3** of the semiconductor memory device of the third embodiment is manufactured, a first hole H**1** and a second hole H**2** are formed in different processes, similar to when the memory cell array **10-2** of the second embodiment is manufactured.

[0115] First, processes up to a first plural material recessing process described with reference to FIG. **11** are performed similar to when the memory cell array **10-2** of the second embodiment is manufactured. FIG. **21** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10-3**. As shown in FIG. **21**, an insulating film **231** including aluminum oxide (AlO) or the like is formed in a surface **230***a* of an insulating layer **230**. For example, an insulating film **371** including oxide and an insulating layer **372** including silicon nitride or the like are formed in a surface **231***a* of the insulating film **231** through atomic layer deposition (ALD) or the like. The minimum thickness of the insulating layer **372** in the Z-direction is set to be larger than the minimum thickness of the insulating film **371** in the Z-direction.

[0116] FIG. **22** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10-3**. As shown in FIG. **22**, an insulating film **375** extending inside the insulating layer **372** in the Z-direction is formed. The insulating film **375** is connected to the insulating film **371**. The insulating film **371** is formed closer to a first side than a first semiconductor portion **48** in the X-direction.

[0117] FIG. **23** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10-3**. As shown in FIG. **23**, a hole H**5** extending inside the insulating layer **372** and the insulating film **371** in the Z-direction is formed. The hole H**5** substantially overlaps the second semiconductor portion **68** in the X-direction. When the hole H**5** is formed, a portion on a second side of the insulating film **375** in the X-direction is removed, and a concave portion is formed in the insulating film **231**.

[0118] FIG. **24** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10-3**. As shown in FIG. **24**, a semiconductor film **401** is integrally formed on a surface **372***a* of the insulating layer **372**, and each of a side surface of the insulating layer **372**, a side surface of the insulating film **371**, and a side surface of the insulating film **231** which are exposed to the hole H**5**. The semiconductor film **401** includes the same material as that of each of the semiconductor films **92** and **94**. FIG. **25** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10-3**. As shown in FIG. **25**, an insulating film **402** and a dummy film **403** including amorphous silicon or the like are formed on the surface of the semiconductor film **401**, a side surface exposed to the hole H**5**, and the bottom face of the concave portion of the insulating film **231**.

[0119] Each of FIGS. **26** and **27** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10-3**. As shown in FIG. **26**, a hole H**6** extending through the insulating film **231** in the Z-direction is formed while removing the semiconductor film **401**, the insulating film **402**, and the dummy film **403** which are positioned at the bottom of the hole H**5**. At the bottom of the hole H**6**, a concave portion is formed in an end portion of the first semiconductor portion **48** in the +Z-direction. Subsequently, the dummy film **403** remaining is removed. As shown in FIG. **27**, the concave portion of the first semiconductor portion **48** is expanded in each of the −Z-direction and the X-direction through, for example, selective etching to form a concave portion **410** connected to the hole H**6** in the Z-direction.

[0120] Each of FIGS. **28** and **29** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10-3**. As shown in FIG. **28**, a dummy film **412** including amorphous silicon or the like is formed on the side surface and the surface of each constituent element exposed to the hole H**6** and the concave portion **410**. Subsequently, as shown in FIG. **29**, an insulating film **415** such as silicon oxide is formed in a space surrounded by the dummy film **412**. A surface **415***a* of the insulating film **415** is positioned between the surface **372***a* of the insulating layer **372** and the surface **371***a* of the insulating film **371** in the Z-direction.

[0121] FIG. **30** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10-3**. As shown in FIG. **30**, the semiconductor film **401**, the insulating film **402**, and the dummy film **412** are recessed in the −Z-direction, and ends in the +Z-direction of the semiconductor film **401**, the insulating film **402**, and the dummy film **412** in the Z-direction are aligned at the same position as the surface **415***a* of the insulating film **415**. Subsequently, an oxide film **420** including silicon oxide or the like is formed so as to cover each of the surface **372***a* of the insulating layer **372**, the semiconductor film **401**, the insulating film **402**, the dummy film **412**, and the insulating film **415**. A concave portion **422** is formed in the oxide film **420** in a portion overlapping the first semiconductor portion **48** and the insulating film **415** in the Z-direction. The width of the concave portion **422** in the X-direction decreases toward the −Z-direction.

[0122] Each of FIGS. **31**, **32**, and **33** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10-3**. For example, only the oxide film **420** in substantially the +Z-direction rather than the insulating film **402** and the dummy film **412** is left through etching or the like as shown in FIG. **31**, and the oxide film **420** in the other portions is removed. As shown in FIG. **32**, a semiconductor layer **424** including, for example, amorphous silicon is formed so as to cover each of the semiconductor film **401**, the insulating film **402**, the dummy film **412**, and the insulating film **415**. A surface **424***a* of the semiconductor layer **424** and a surface **372***a* of the insulating layer **372** are set to be on substantially the same plane. As shown in FIG. **33**, an insulating film **426** including, for example, silicon oxide is formed on the surface **424***a* of the semiconductor layer **424** and the surface **372***a* of the insulating layer **372**. Subsequently, although not shown in the drawing, an upper electrode and the like are processed. Through the processing, the insulating film **426** is removed, so that components in a state similar to that shown in FIG. **32** are obtained.

[0123] Each of FIGS. **34** and **35** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10-3**. For example, the insulating layer **372** is removed as shown in FIG. **34** using a medicinal solution, etching, or the like. Subsequently, as shown in FIG. **35**, a barrier film **430** that covers the insulating film **371**, the insulating film **375**, the oxide film **420**, and the semiconductor layer **424** is formed. A metal layer **432** that covers the barrier film **430** is formed. The metal layer **432** includes, for example, tungsten.

[0124] FIG. **36** is a cross-sectional view showing an example of a manufacturing process for the memory cell array **10-3**. As shown in FIG. **36**, the metal layer **432** and the barrier film **430** are recessed in the −Z-direction, and an insulating interlayer **440** that covers the recessed metal layer **432** and barrier film **430** is formed. The insulating interlayer **440** is formed of, for example, silicon oxide or the like.

[0125] The plurality of first dummy layers **238** of the first intermediate stack **240** are removed using, for example, a medicinal solution or the like at a predetermined timing for the over-described processes. A conductive material including the same material as that of the first conductive layer **23** is supplied to a region **331** from which each of the first dummy layers **238** is removed.

[0126] The memory cell array **10-3** shown in FIG. **20** can be manufactured by proceeding with the over-described processes. The semiconductor memory device of the third embodiment is formed by performing known pre-processing before the over-described processes and performing known post-processing after the over-described processes. However, the method of manufacturing the semiconductor memory device of the third embodiment is not limited to the over-described method.

[0127] Operational effects of the semiconductor memory device of the third embodiment described over will be described. Similar to the semiconductor memory device of the second embodiment, the semiconductor memory device of the third embodiment includes the first semiconductor portion **48** including a first semiconductor of single-crystal with a defect level of hardly any defects in a region **44** including a center **40***c* equidistant from a first end **40***e* and a second end **40***f* when seen in the Z-direction. A first channel portion **42** is formed of a first semiconductor of single-crystal with a defect level of hardly any defects, so that variations in a threshold voltage of a plurality of memory cell transistors MT are suppressed. Therefore, according to the semiconductor memory device of the third embodiment, electrical characteristics can be improved.

[0128] The semiconductor memory device of the third embodiment includes the insulating portion **70** in a region **64** including a center **60***c* equidistant from a third end **60***e* and a fourth end **60***f* when seen in the Z-direction. The semiconductor memory device of the third embodiment includes the second semiconductor portion **68** including a second semiconductor of poly-crystal between the insulating portion **70** and two second conductive layers **26** functioning as a selected gate line SGD in the X-direction. Since a second channel portion **62** adjacent to the selected gate line SGD in the X-direction has a thin film channel having a hollow structure, a deterioration in cut-off characteristics is suppressed and the occurrence of a defective operation of the selected gate line SGD is prevented. Therefore, according to the semiconductor memory device of the third embodiment, electrical characteristics can be improved.

[0129] Although embodiments of the present invention have been described over, those embodiments are described as examples, and do not limit the scope of the invention. Those embodiments may be embodied in other various modes, and may be variously omitted, substituted, and modified without departing from the scope of the invention. Those embodiments and modification thereof are within the scope and the gist of the invention, and are within the scope of the invention described in the scope of claims and the equivalent thereof.

[0130] For example, the insulating portions **70** of the semiconductor memory device of the second and third embodiments may be constituted by an insulating material other than air, or may be formed of an insulator such as silicon oxide.

[0131] For example, the first insulating layers **25** of the semiconductor memory devices of the over-described embodiments may be constituted by, for example, an air gap.

[0132] For example, in a semiconductor memory device of an embodiment different from the over-described embodiments, each of the two second columnar bodies **60** may further include a fifth insulating film of a single layer which is provided between the second channel portion **62** and three second conductive layers **26** in the X-direction. That is, each of the two second columnar bodies **60** may include the fifth insulating film instead of the third insulating film **72**, the second charge storage film **74**, and the fourth insulating film **76**. The fifth insulating film is formed of, for example, silicon oxide.

Claims

1. A method of manufacturing a semiconductor memory device, the method comprising: forming a stack by alternately stacking first insulating layers and second insulating layers in a first direction which is a thickness direction of a substrate; forming a hole extending in the first direction in the stack; supplying a first semiconductor to the hole; supplying a second semiconductor to the hole after supplying the first semiconductor; removing the first insulating layers; supplying first conductive material to regions where the first insulating layers are removed, forming a contact plug on the second semiconductor; and forming a bit line electrically connecting to the contact plug, wherein the second semiconductor faces an uppermost layer of the first conductive material, the first semiconductor faces, in a second direction, more layers of the first conductive material compared to the second semiconductor, the second direction being perpendicular to the first direction, and a first film thickness of the first semiconductor in the second direction intersecting the first direction at an upper surface of an uppermost layer of the first conductive material among layers of the first conductive materials facing to the first semiconductor is different from a second film thickness of the second semiconductor in the second direction at a lower surface of a bottom layer of the first conductive material facing to the second semiconductor.

2. The method of manufacturing a semiconductor memory device according to claim 1, wherein a lowest point of the second semiconductor is lower than a lower face of the uppermost layer of the first conductive material in the first direction.

3. The method of manufacturing a semiconductor memory device according to claim 1, wherein the uppermost layer of the first conductive material is a select gate.

4. The method of manufacturing a semiconductor memory device according to claim 1, wherein the second semiconductor faces, in the second direction, a second highest layer of the first conductive material, the uppermost layer and the second highest layer of the first conductive material are select gates.

5. The method of manufacturing a semiconductor memory device according to claim 1, wherein the first semiconductor faces, in the second direction, layers of the first conductive material including word lines.

6. The method of manufacturing a semiconductor memory device according to claim 1, wherein the first semiconductor is single-crystal.

7. The method of manufacturing a semiconductor memory device according to claim 1, wherein the second semiconductor is poly-crystal.

8. The method of manufacturing a semiconductor memory device according to claim 1, wherein the first semiconductor has less-grain boundaries compared to the second semiconductor.

9. The method of manufacturing a semiconductor memory device according to claim 1, wherein a distance between outer edges of the first semiconductor in the second direction at the upper surface of the uppermost layer of the first conductive material is substantially the same as a distance between outer edges of the second semiconductor in the second direction at the lower surface of the bottom layer of the first conductive material facing to the second semiconductor.

10. The method of manufacturing a semiconductor memory device according to claim 1, wherein a first film thickness of the first semiconductor in the second direction intersecting the first direction at an upper surface of an uppermost layer of word lines is different from a second film thickness of the second semiconductor in the second direction at a lower surface of an uppermost layer of a select gate.

11. The method of manufacturing a semiconductor memory device according to claim 1, wherein a lowest point of the contact plug is lower than a highest point of the second semiconductor.

12. The method of manufacturing a semiconductor memory device according to claim 1, further comprising: supplying a third semiconductor to the hole, before supplying the first semiconductor to the hole.

13. The method of manufacturing a semiconductor memory device according to claim 12, wherein the first semiconductor has a maximum film thickness in the second direction intersecting the first direction smaller than a minimum film thickness of the third semiconductor in the second direction.

14. The method of manufacturing a semiconductor memory device according to claim 12, wherein the hole reaches the substrate.

15. The method of manufacturing a semiconductor memory device according to claim 12, wherein supplying the first semiconductor includes supplying the first semiconductor in the hole by

epitaxial growth.
16. The method of manufacturing a semiconductor memory device according to claim 1, further comprising: supplying a third insulating material to an inner side of the second semiconductor.
17. The method of manufacturing a semiconductor memory device according to claim 1, wherein the semiconductor memory device is a NAND flash memory.
18. A method of manufacturing a semiconductor memory device, the method comprising: forming a stack by alternately stacking first insulating layers and second insulating layers in a first direction which is a thickness direction of a substrate; forming a hole extending in the first direction in the stack; supplying a first semiconductor to the hole; supplying a second semiconductor to the hole after supplying the first semiconductor; removing the first insulating layers; supplying first conductive material to regions where the first insulating layers are removed; forming a contact plug on the second semiconductor; and forming a bit line electrically connecting to the contact plug, wherein the second semiconductor faces an uppermost layer of the first conductive material, the first semiconductor faces, in a second direction, more layers of the first conductive material compared to the second semiconductor, the second direction being perpendicular to the first direction, and a first film thickness of the first semiconductor in the second direction intersecting the first direction at an upper surface of an uppermost layer of word lines is different from a second film thickness of the second semiconductor in the second direction at a lower surface of an uppermost layer of a select gate.
19. The method of manufacturing a semiconductor memory device according to claim 18, wherein the first semiconductor is single-crystal.
20. The method of manufacturing a semiconductor memory device according to claim 18, wherein the second semiconductor is poly-crystal.
21. The method of manufacturing a semiconductor memory device according to claim 18, wherein a lowest point of the contact plug is lower than a highest point of the second semiconductor.
22. The method of manufacturing a semiconductor memory device according to claim 18, further comprising: supplying a third semiconductor to the hole, before supplying the first semiconductor to the hole.
23. The method of manufacturing a semiconductor memory device according to claim 22, wherein the first semiconductor has a maximum film thickness in the second direction intersecting the first direction smaller than a minimum film thickness of the third semiconductor in the second direction.
24. The method of manufacturing a semiconductor memory device according to claim 18, wherein the semiconductor memory device is a NAND flash memory.
25. A method of manufacturing a semiconductor memory device, the method comprising: forming a stack by alternately stacking first insulating layers and second insulating layers in a first direction which is a thickness direction of a substrate; forming a hole extending in the first direction in the stack; supplying a first semiconductor to the hole; supplying a second semiconductor to the hole after supplying the first semiconductor; removing the first insulating layers; supplying first conductive material to regions where the first insulating layers are removed; forming a contact plug on the second semiconductor; and forming a bit line electrically connecting to the contact plug, wherein the second semiconductor faces an uppermost layer of the first conductive material, the first semiconductor faces, in a second direction, more layers of the first conductive material compared to the second semiconductor, the second direction being perpendicular to the first direction, and a first cross-sectional area of the first semiconductor along a plane that is perpendicular to the first direction at an upper surface of an uppermost layer of word lines is different from a second crosssectional area of the second semiconductor along a plane that is perpendicular to the first direction at a lower surface of an uppermost layer of a select gate.
26. The method of manufacturing a semiconductor memory device according to claim 25, wherein the first semiconductor is single-crystal.
27. The method of manufacturing a semiconductor memory device according to claim 25, wherein

the second semiconductor is poly-crystal.

28. The method of manufacturing a semiconductor memory device according to claim 25, wherein a lowest point of the contact plug is lower than a highest point of the second semiconductor.

29. The method of manufacturing a semiconductor memory device according to claim 25, wherein the semiconductor memory device is a NAND flash memory.